Receipt

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor	:	**Atsushi NISHIZAWA**
Serial No	:	**09/751,979**
Filed	:	**January 23, 2001**
Title	:	**MANUFACTURING METHOD OF SEMICONDUCTOR...**
Group Art Unit	:	**1765**

May 4, 2001

Attn: Customer Corrections Division
Assistant Commissioner for Patents
Washington, D.C. 20231

REQUEST FOR CORRECTED FILING RECEIPT

SIR:

We received the filing receipt on the above-referenced case, copy enclosed, wherein the **ASSIGNMENT FOR PUBLISHED PATENT APPLICATION** was incorrectly listed as: **NEC CORP.** Please change the same to read: **NEC CORPORATION.** Also the **TITLE** was incorrectly listed as: **MANUFACTURING METHOD SEMICONDUCTOR INTERGRATED CIRCUIT INCLUDING SIMULTANEOUS FORMATION OF VIA HOLE REACHING METAL WIRING AND CONCAVE GROOVE IN INTERLAYTER....** Please change the same to read: **MANUFACTURING METHOD OF SEMICONDUCTOR INTERGRATED CIRCUIT INCLUDING SIMULTANEOUS FORMATION OF VIA HOLE REACHING METAL WIRING AND CONCAVE GROOVE IN INTERLAYER FILM AND SEMICONDUCTOR INTERGRATED CIRCUIT MANUFACTURED WITH THE MANUFACTURING METHOD.**

Any fee, due as a result of this paper not fully covered by an enclosed check, may be charged on Deposit Account No. 08-1634.

Respectfully submitted,

Samson Helfgott
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Docket No.:18.159
SH:eju:FILREC

Any fee due with this paper, not fully served by an enclosed check, may be charged on deposit Acct. No. 08-1634

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS FIRST CLASS MAIL IN AN ENVELOPE ADDRESSED TO: COMMISSIONER OF PATENTS AND TRADEMARKS, WASHINGTON, D.C. 20231, ON THE DATE INDICATED BELOW.

BY _____

DATE May 4, 2001

UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20231
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY.DOCKET.NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/751,979	12/29/2000	1765	710	NECW 18.159	6	12	2

CONFIRMATION NO. 9046

FILING RECEIPT

OC000000005913685

HELFGOTT & KARAS, P.C.
60th Floor
Empire State Building
New York, NY 10118-0110

Date Mailed: 03/28/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. **If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the PTO processes the reply to the Notice, the PTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).**

Applicant(s)

Atsushi Nishizawa, Tokyo, JAPAN;

Assignment For Published Patent Application

NEC ~~Corp.~~; CORPORATION

Continuing Data as Claimed by Applicant

Foreign Applications

JAPAN 2000-009221 01/18/2000

If Required, Foreign Filing License Granted 03/27/2001

Projected Publication Date: 07/19/2001

Non-Publication Request: No

Early Publication Request: No

Title

OF

Manufacturing method semiconductor integrated circuit including simultaneous formation of via hole reaching metal wiring and concave groove in ~~interlayer~~ film and semiconductor integrated circuit manufactured with the manufacturing method

INTERLAYER

Preliminary Class

438

Data entry by : IBRAHIM, SADIE **Team :** OIPE **Date:** 03/28/2001